



December 12, 2013

Subject: RoHS Directive (2002/95/EC) / RoHS II Directive (2011/65/EU) Compliance

This letter is to hereby declare that the following products are manufactured in accordance with the EU RoHS (Restriction of Hazardous Substances) directive restricting the use of certain materials (below).

RoHS Substances:

Lead (Pb), Mercury (Hg), Cadmium (Cd), Hexavalent Chromium (Cr(VI)), Polybrominated Biphenyls (PBBs), Polybrominated Diphenyl Ethers (PBDEs including Deca-BDE)

Applicable Product Families:

| Product Family | SMD/THD | Package/Series | RoHS Exemption | Effective Date |
|--------------------|---------|---|--|------------------|
| LSI | SMD | VBGA-T, VBGA-W, SBGA-T, SBGA-W, VCSP, UCSP | - | Jan, 2004 (0401) |
| | | HRP, TO252S | 7(a) : Pb in high melting temperature type solders | |
| | | QFP, SQFP, VQFP, TQFPV, UQFP, TQFPU, VQFN-V, UQFN-V, MSOP, SOP, SSOP, SSOP-A, SSOP-B, TSSOP, VSOF, HVSO, WSO, HSON, SSON, VSON, USON, SOT223-5, HSOP, HTSOP-J, HTSSOP-A, HTSSOP-B, HTSSOP-C | Depend on Part No. (- / 7(a) : Pb in high melting temperature type solders) | |
| | THD | TO220CP | 7(a) : Pb in high melting temperature type solders | |
| Transistor | SMD | VMN3, VMT3, VMT6, EMT3F, EMT3, EMT5, EMT6, UMT3F, UMT3, UMT5, UMT6, SST3, SMT3, SMT5, SMT6, TSST8, TUMT3, TUMT5, TUMT6, WEMT6, TSMT3, TSMT5, TSMT6, TSMT8, MPT6, SOP8 | - | Jun, 2004 (0423) |
| | | MPT3, CPT3, TCPT3, LPTS, LPTL | 7(a) : Pb in high melting temperature type solders | |
| | THD | SPT3, TO-220FMN, ATV, TO-3PF | - 7(a) : Pb in high melting temperature type solders | |
| Diode | SMD | GMD2, VMN2, VMD2, VMD3, KMD2, EMD2, EMD3, EMD4, EMD5, EMD6, UMD2, UMD3, UMD4, UMD5, UMD6, SMD3, SMD5, SMD6, SSD3, TSMD5, TSMD6, TUMD2, TUMD5, HMD8, HMD12, CPD | - | Jun, 2004 (0423) |
| | | PMDU, PMDT, PMDS, LPDS | 7(a) : Pb in high melting temperature type solders | |
| | | LLDS | 7(c)-f: Pb in the glass of electronic components | |
| | THD | MSR, TO-220FN, TO-220NFM | - | |
| | | MSD | 7(c)-f: Pb in the glass of electronic components | |
| Resistor | SMD | PMR, PML Series | - | |
| | | MCR, UCR, LTR, ESR, KTR, TRR, MNR, RCN Series | 7(c)-f: Pb in the glass of electronic components | |
| Tantalum Capacitor | SMD | TCS, TC, TCT, TCTO, TCO Series | - | |
| | | TCFG Series | 7(a) : Pb in high melting temperature type solders | |
| LED | SMD | SML Series | - | Originally R/C |
| | THD | SLA, SLB, SLC, SLI, SLR, SPR Series | - | Apr, 2004 (0414) |
| LED Display | SMD | LF Series | - | Apr, 2004 (0415) |
| | THD | LA, LB, LC, LD, LAP, LAB Series | - | |
| Sensor | SMD | SIM-0, SCM-, SML-, RPM Series | - | Apr, 2004 (0415) |
| | THD | RPI-0, RPI-10 Series, RPI, RPM-2, RPR, RPT, SIM, SIR Series | - | |
| Laser Diode | THD | RLD Series | Depend on Part No. (- / 7(a) : Pb in high melting temperature type solders) | Originally R/C |
| Photo Link Module | SMD | RPM5300-H12, RPM5300-H14, RPM5500-H12, RPM5500-H14, RPMS1001, RPMS2001, RPM□□□ Series | - | Apr, 2004 (0415) |
| | THD | RPM6900, RPM7100, RPM7200 Series | - | |
| Power Module | - | Single in-line(SIP), Leadless assembly, Surface mounted type | 7(a) : Pb in high melting temperature type solders 7(c)-f: Pb in the glass of electronic components | Dec, 2004 (0453) |

* Originally R/C = Originally RoHS Compliant

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